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TITLE: Semiconductor package including double underfill area

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PATENT-FAMILY:

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APPLICATION-DATA:

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INT-CL_(IPC): H01L021/60

ABSTRACTED-PUB-NO: KR2001054743A

BASIC-ABSTRACT: NOVELTY - A semiconductor package including double underfill area is provided to prevent a fillet part of underfill area from cracking.

DETAILED DESCRIPTION - A bonding pad(112) is formed on a semiconductor chip(110). The bonding pad(112) is connected with the semiconductor chip(110) through a bump(120). The semiconductor chip(110) is composed of a substrate(130), an external connection terminal(140) such as solder balls, and a double underfill area(150). The double underfill area(150) consists of the first underfill area(154) and the second underfill

area(156). The first
underfill area(154) locates between the semiconductor
chip(110) and the
substrate(130), and is filled with liquid type of a sort of
epoxy material.

The second underfill area(156) positions around the
semiconductor chips(110),
and it is reclaimed with a sort of silicon material.

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS:
SEMICONDUCTOR PACKAGE DOUBLE AREA

DERWENT-CLASS: U11

EPI-CODES: U11-D01C9;



